

Silicon Carbide Schottky Diode

IDW15G120C5B

5th Generation thinQ!™ 1200 V SiC Schottky Diode

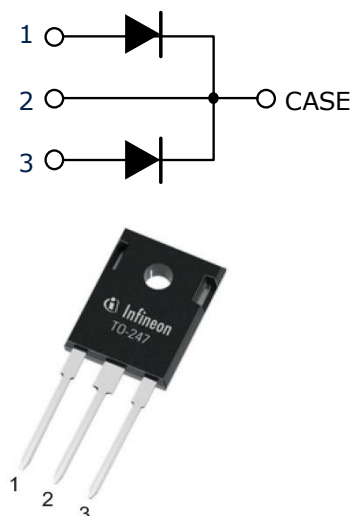
Final Datasheet

Rev. 2.0 2014-06-10

thinQ!™ SiC Schottky Diode

Features:

- Revolutionary semiconductor material - Silicon Carbide
- No reverse recovery current / No forward recovery
- Temperature independent switching behavior
- Low forward voltage even at high operating temperature
- Tight forward voltage distribution
- Excellent thermal performance
- Extended surge current capability
- Specified dv/dt ruggedness
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free lead plating; RoHS compliant



Benefits

- System efficiency improvement over Si diodes
- Enabling higher frequency / increased power density solutions
- System size/cost savings due to reduced heatsink requirements and smaller magnetics
- Reduced EMI
- Highest efficiency across the entire load range
- Robust diode operation during surge events
- High reliability
- RelatedLinks: www.infineon.com/sic



Applications

- Solar inverters
- Uninterruptable power supplies
- Motor drives
- Power Factor Correction



Package pin definitions

- Pin 1 – anode 1
- Pin 2 and backside – cathode
- Pin 3 – anode 2



Key Performance and Package Parameters (leg/device)

Type	V _{DC}	I _F	Q _C	T _{j,max}	Marking	Package
IDW15G120C5B	1200V	7.5 / 15 A	41 / 82 nC	175°C	D1512B5	PG-TO247-3

1) J-STD20 and JESD22

Table of Contents

Description.....	2
Table of Contents.....	3
Maximum ratings.....	4
Thermal Resistances	4
Electrical Characteristics.....	5
Electrical Characteristics diagram	6
Package Drawings	9
Revision History	10
Disclaimer.....	10

Maximum ratings

Parameter	Symbol	Value (leg/device)	Unit
Repetitive peak reverse voltage	V_{RRM}	1200	V
Continuous forward current for $R_{th(j-c,max)}$ $T_C = 154^{\circ}\text{C}$, $D=1$ $T_C = 135^{\circ}\text{C}$, $D=1$ $T_C = 25^{\circ}\text{C}$, $D=1$	I_F	7.5 / 15 11 / 23 24 / 49	A
Surge non-repetitive forward current, sine halfwave $T_C=25^{\circ}\text{C}$, $t_p=10\text{ms}$ $T_C=150^{\circ}\text{C}$, $t_p=10\text{ms}$	$I_{F,SM}$	85 / 170 80 / 160	A
Non-repetitive peak forward current $T_C = 25^{\circ}\text{C}$, $t_p=10 \mu\text{s}$	$I_{F,max}$	711 / 1422	A
i^2t value $T_C = 25^{\circ}\text{C}$, $t_p=10 \text{ ms}$ $T_C = 150^{\circ}\text{C}$, $t_p=10 \text{ ms}$	$\int i^2 dt$	36 / 143 32 / 128	A ² s
Diode dv/dt ruggedness $V_R=0\ldots960 \text{ V}$	dv/dt	80	V/ns
Power dissipation for $R_{th(j-c,max)}$ $T_C = 25^{\circ}\text{C}$	P_{tot}	100 / 200	W
Operating and storage temperature	$T_j; T_{stg}$	-55...175	$^{\circ}\text{C}$
Soldering temperature, wavesoldering only allowed at leads 1.6mm (0.063 in.) from case for 10 s	T_{sld}	260	$^{\circ}\text{C}$
Mounting torque M3 and M4 screws	M	0.7	Nm

Thermal Resistances

Thermal Resistances						
Parameter	Symbol	Conditions	Value (leg/device)			Unit
			min.	typ.	max.	
Characteristic						
Diode thermal resistance, junction – case	R _{th(j-c)}		-	1.1/0.6	1.5/0.8	K/W
Thermal resistance, junction – ambient	R _{th(j-a)}	leaded	-	-	62	K/W

Electrical Characteristics

Static Characteristic, at T_j=25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value (leg/device)			Unit
			min.	typ.	max.	
DC blocking voltage	V _{DC}	T _j = 25°C	1200	-	-	V
Diode forward voltage	V _F	I _F = 7.5/15 A, T _j = 25°C	-	1.4	1.65	V
		I _F = 7.5/15 A, T _j = 150°C	-	1.7	2.30	
Reverse current	I _R	V _R = 1200V, T _j = 25°C		4 / 8	62 / 124	μA
		V _R = 1200V, T _j = 150°C		22 / 44	320 / 640	

Dynamic Characteristics, at T_j=25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value (leg/device)			Unit
			min.	typ.	max.	
Total capacitive charge	Q _C	V _R = 800V, T _j = 150°C & 25°C $Q_C = \int_0^{V_R} C(V) dV$	-	41 / 82	-	nC
Total Capacitance	C	V _R = 1 V, f = 1 MHz	-	525 / 1050	-	pF
		V _R = 400 V, f = 1 MHz	-	37 / 74	-	
		V _R = 800 V, f = 1 MHz	-	29 / 59	-	

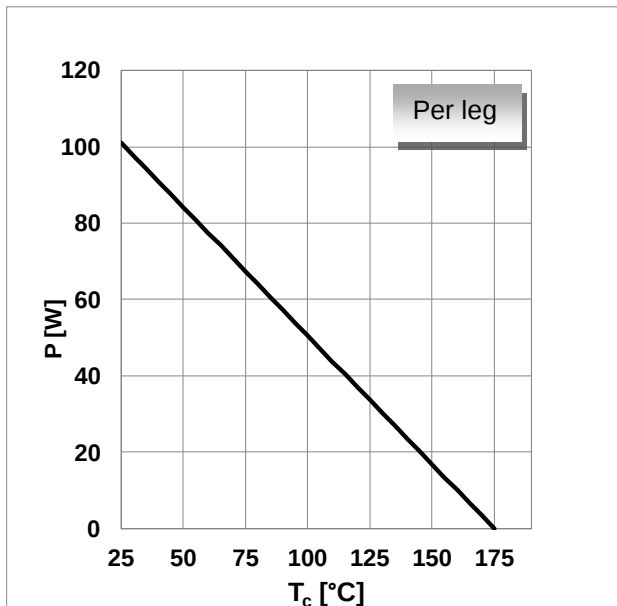


Figure 1. Power dissipation per leg as function of case temperature, $P_{\text{tot}} = f(T_c)$, $R_{\text{th(j-c),max}}$

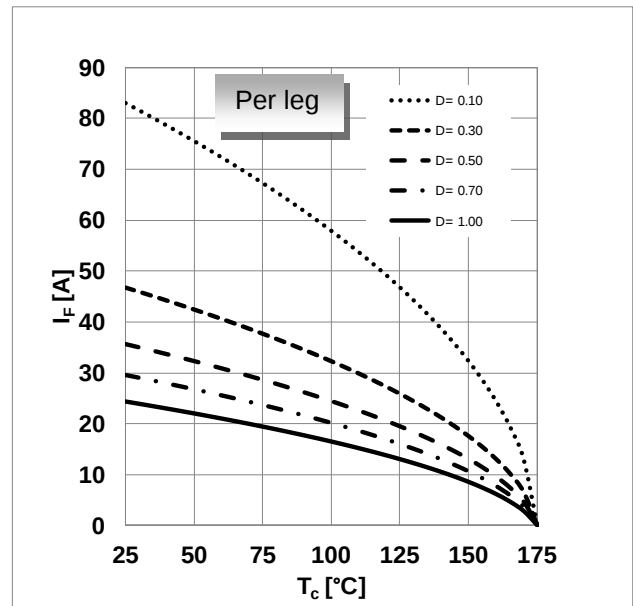


Figure 2. Diode forward current per leg as function of temperature, parameter: $T_j \leq 175^\circ\text{C}$, $R_{\text{th(j-c),max}}$, D =duty cycle, V_{th} , R_{diff} @ $T_j = 175^\circ\text{C}$

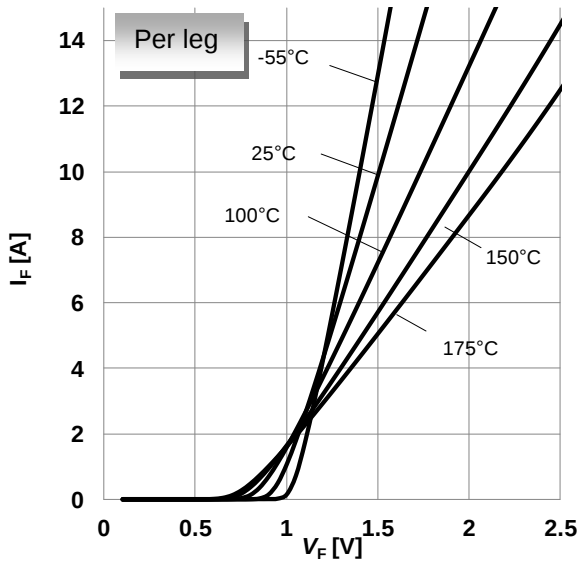


Figure 3. Typical forward characteristics per leg, $I_F = f(V_F)$, $t_p = 10 \mu\text{s}$, parameter: T_j

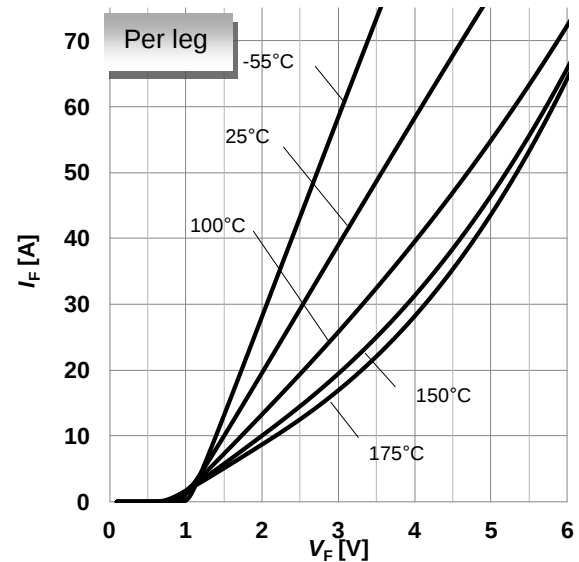


Figure 4. Typical forward characteristics in surge current per leg, $I_F = f(V_F)$, $t_p = 10 \mu\text{s}$, parameter: T_j

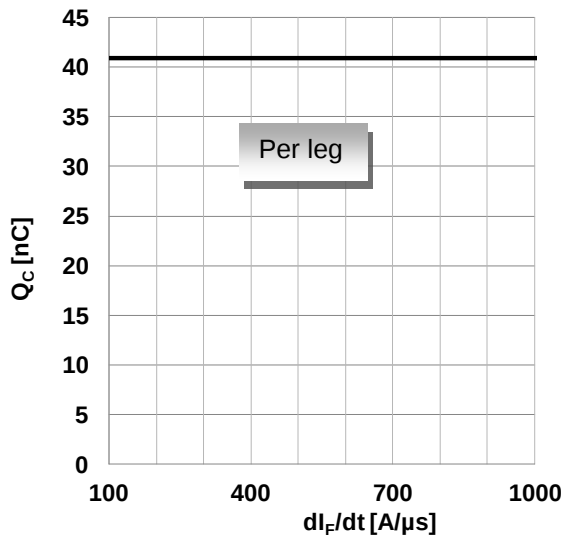


Figure 5. Typical capacitive charge per leg as function of current slope¹, $Q_c = f(di_F/dt)$, $T_j = 150^\circ\text{C}$

1) guaranteed by design.

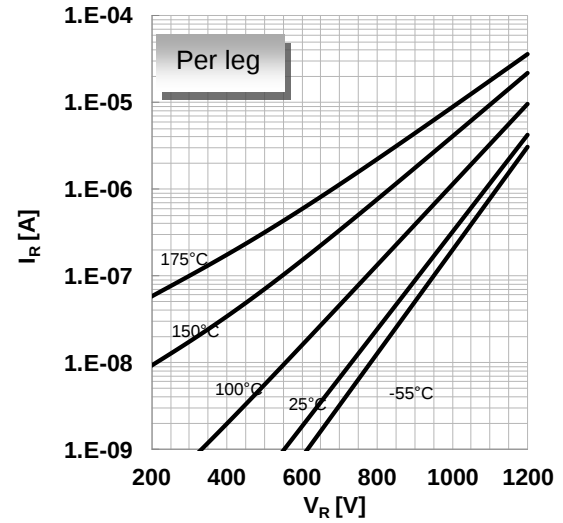


Figure 6. Typical reverse characteristics per leg, $I_R = f(V_R)$, parameter: T_j

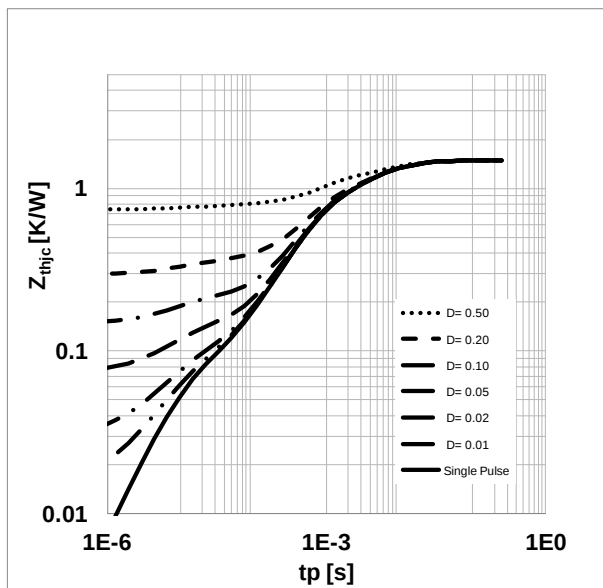


Figure 7. Max. transient thermal impedance per leg, $Z_{th,jc} = f(t_p)$, parameter: $D = t_p/T$

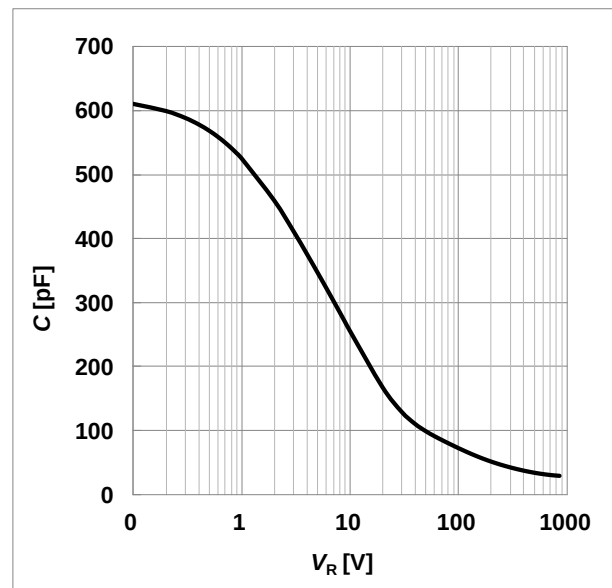


Figure 8. Typical capacitance per leg as function of reverse voltage, $C = f(V_R)$; $T_j = 25^\circ\text{C}$; $f = 1\text{ MHz}$

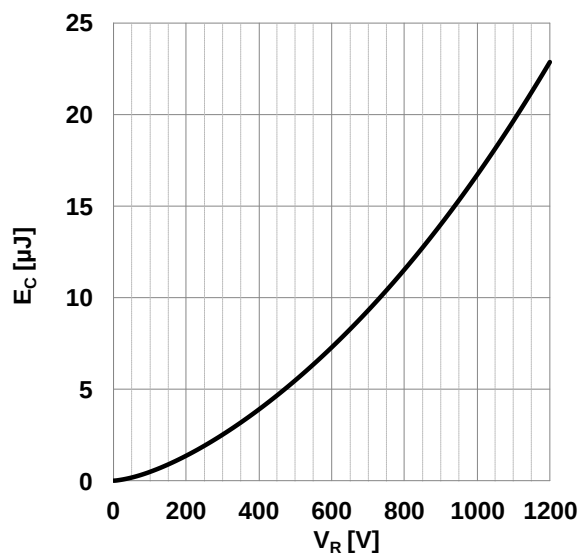
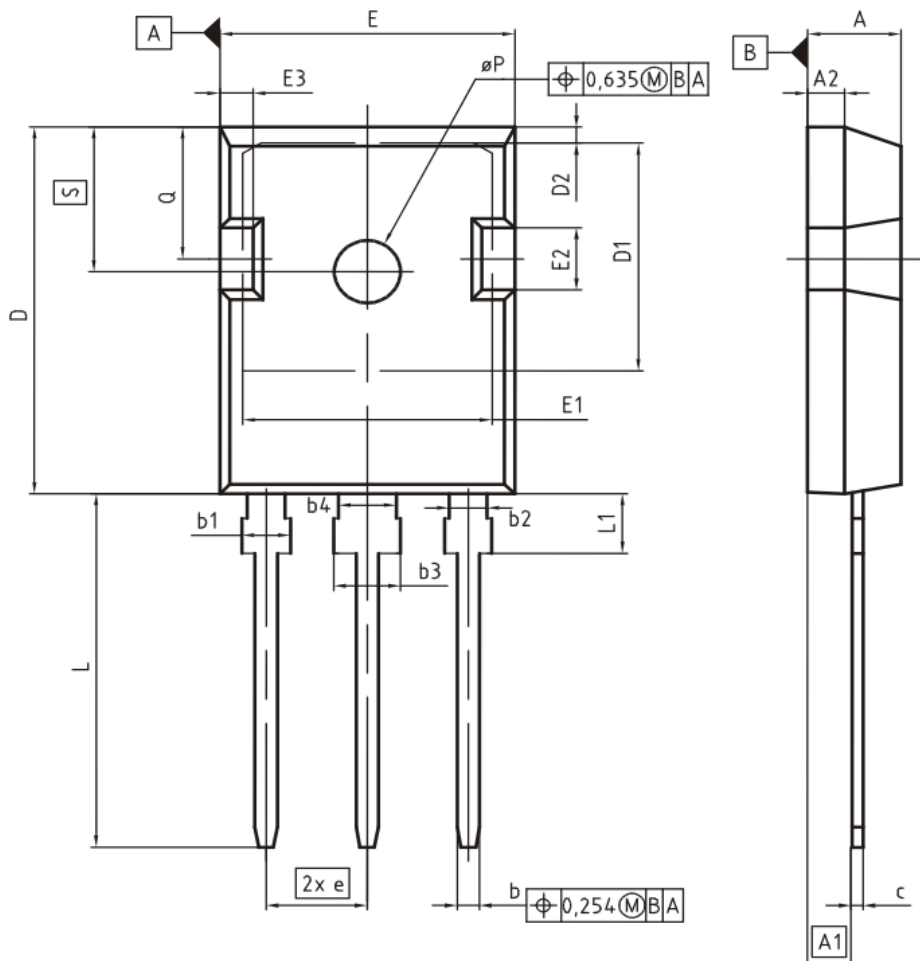


Figure 9. Typical capacitively stored energy as function of reverse voltage, per leg, $E_C=f(V_R)$

PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44 (BSC)		0.214 (BSC)	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

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2.0	-	Final data sheet

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